

--33. A method comprising:

placing a predetermined solder pattern onto a pad on a substrate;

heating said predetermined solder pattern; and

determining that said solder is lead-free if said predetermined solder pattern after heating is in substantially a same pattern as said predetermined solder pattern before heating.--

--34. The method of claim 33, wherein said predetermined solder pattern

comprises at least one symbol.--

--35. The method of claim 33, wherein said substrate comprises a printed circuit

board.--